

Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f., UL94V-0
- 1.2 Contact: Copper alloy, t=0.15
- 1.3 Shell: copper alloy, t=0.25

2. Specification:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 0.8 Kgf Max.
- 2.7 Temperature range: -30°C ~ 80°C
- 2.8 Durability: 3,000 cycles

广东星坤科技股份有限公司

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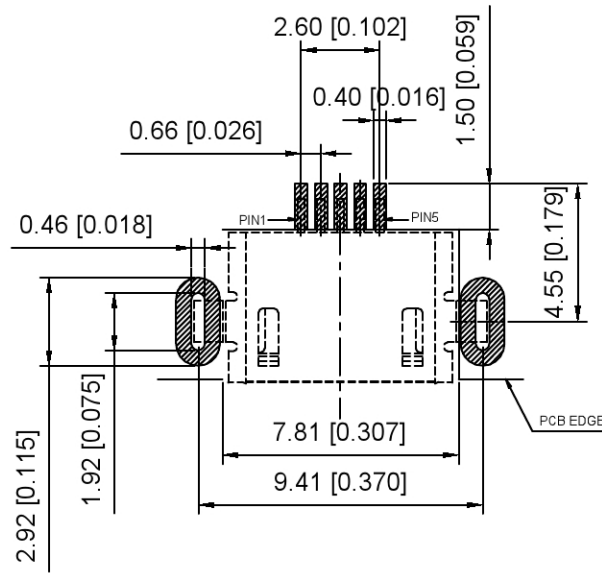
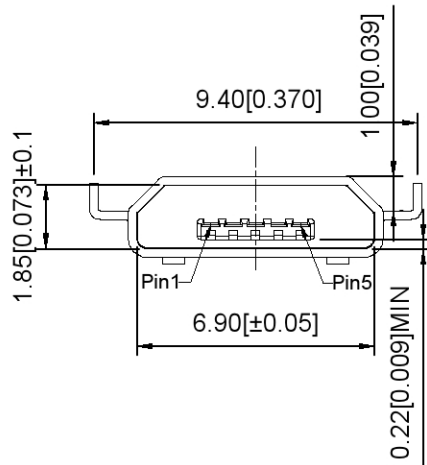
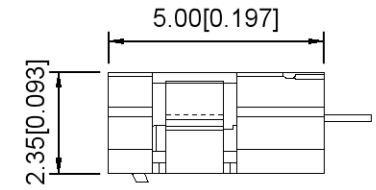
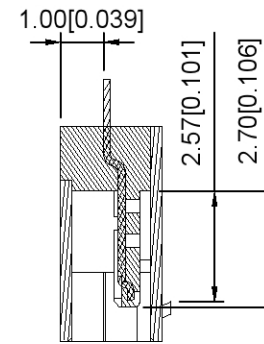
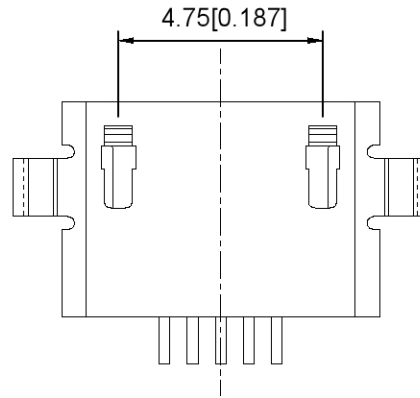
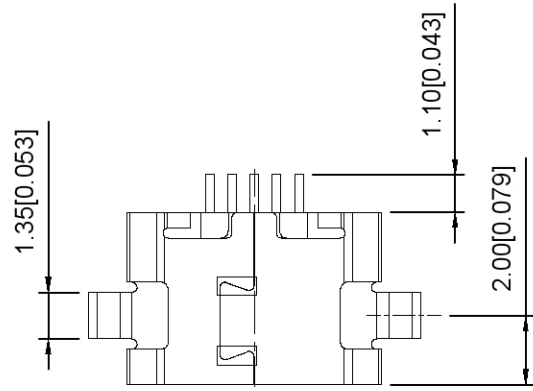
文件工程章

REVISIONS

UNSPECIFIED TOLERANCES

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DSND	DATE	SCALE: N/A	MODEL TYPE: MICRO USB
DWN	DATE	VIEW:	PART NO.:
CHKD	DATE	UNIT: mm/in	DWG NO.:
APPD	DATE	SIZE: A4	U253-05XX-4BH83-XB
KXB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT 1.0g
			SHEET 1/1
			REVISION A0



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0.80 [0.031]

RECOMMENDED PCB LAYOUT

REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
ANGLAR				±5°
L ≤ 4				±0.2
4 < L ≤ 16				±0.3
16 < L ≤ 63				±0.4
L > 63				±0.5

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	MICRO USB
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			U253-05XX-4BH83-XB
		WEIGHT	SHEET
		1.0g	1/1
		REVISION	A0

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